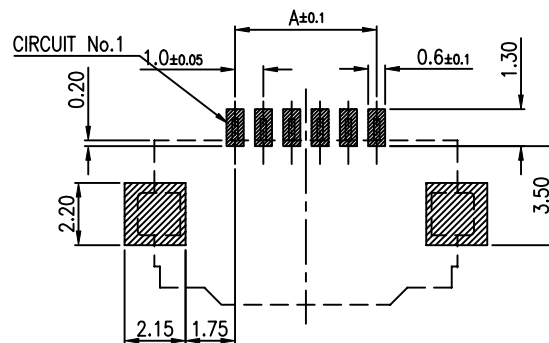
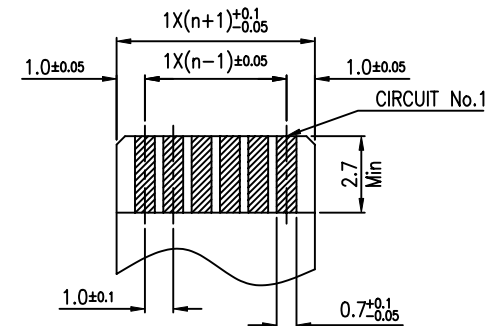
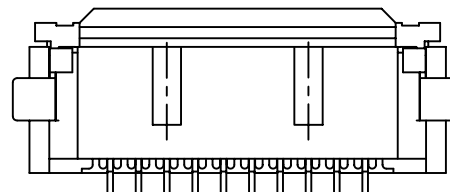
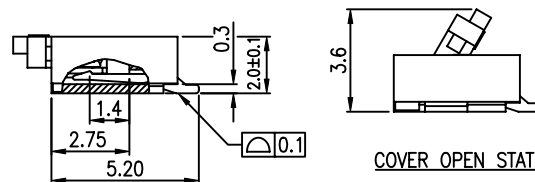


CKT	DIM.A	DIM.B	DIM.C
006	5.00	7.06	10.7
008	7.00	9.06	12.7
010	9.00	11.06	14.7
012	11.00	13.06	16.7



RECOMMENDED PC BOARD PATTERN DIM.(REF.)



APPLICABLE FPC RECOMMENDED DIM.
(THICKNESS: 0.3±0.03)

NOTES:

- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0.
 - ACTUATOR: THERMOPLASTIC, HIGH TEMP., UL94V-0.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
- FINISH:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - CONTACT AREA AND SOLDER TAIL: GOLD FLASH OVERALL
 - FITTING NAIL:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - MATTE TIN PLATING 100u" MIN. OVERALL
- REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP. FOR 10 SECONDS MAX.
- SPEC. PLS. REFER TO GS-12-579.
- PACKAGE PLS. REFER TO GS-14-1331.
- PART NUMBER DESCRIPTION:

10089709-XXX 0 1 0 LF
 NO OF CONTACTS(CKT) ——— X ——— LEAD FREE
 PACKING ——— 0: TAPE & REEL ——— COLOR
 ——— X: HOUSING ACTUATOR
 ——— 0: NATURAL BLACK
 PLATING
 1: GOLD FLASH OVERALL

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI	
ltr	ecn no	dr	date	linear	.X ± 0.25	projection		title	www.fciconnect.com
A	T08-1182	WL	11/06/08		.XX ± 0.15			1.0mm FPC CONN. SMT	
B	T08-1196	WL	12/10/08		.XXX ± 0.10			R/A B/C TYPE	
C	T09-1001	WL	01/05/09	angles	0° ± 2°			product family	FPC
D	T09-1005	WL	01/20/09	dr	LEIF SHEN	08-06-18		size	dwg no
E	T09-1132	WL	10/15/09	enr	DENNIS GOH	08-10-20		scale	
F	T10-0046	WL	04/15/10	chr	DENNIS GOH	08-10-20		A4	10089709
				appd	JOEY NG	08-10-20			
sheet index	revision sheet	F	1					cage code	22526